

Туре	Ag [*] Aİ [*]	V _{DRM} / V _{RRM}	V _{DSM} / V _{RSM} [V]	<i>I_{T(AV)}</i> [A]	Chip Size [mm] x [mm]	Package Options	• •
CWP 130-	14 🗹 🗸	1400	1500	204	19.05 15.4	sawn on foil vnsawn wafer vin waffle pack v	
	*Frontside options					*Please contact IXYS chip sales	

Mechanical Parameters

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) * = Stitchbonds Number / Ø [µm] Metallization backside Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack

cm² 1.96 2.93 cm² 150 mm 380 μm Si 42 Glassivation solderable: Ti / Ni / Ag * bondable: ΑI Cathode Gate / 500 1 / 500 solderable (only): Ti / Ni / Ag * Ø 0.4-1.0 mm < 6 month < 2 year

in org. container, in dry nitrogen in org. container, in dry nitrogen <2 year in org. container, in dry nitrogen -40... 40 °C T_{stq}

Features

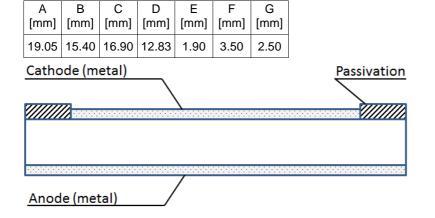
- planar design (non-mesa)
- ultra rugged for easy assembly (flat backside)
- excellent long term stability
- very low leakage current
- very low forward voltage drop

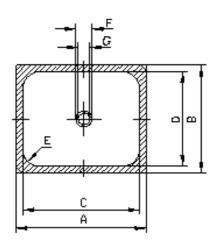
Applications

- DC motor control
- AC power control
- Softstrart AC motor controller
- Light, heat and temperature control
- Solid state relays
- Controlled rectifier circuits

*Sinterable top/bottom side on request

Dimensions







	Ratings				
Symbol	Conditions	min.	typ.	max.	
I _R	$V_D = Vr = Vrr$				m/
		$T_{V,I} = 150^{\circ}C$		30	
V_{τ}	$I_{T} = 350 \text{ A}$		44	1.21	
V _{T0}	For nower-loss	T _{v,i} = 150 °C s calculations only	- (1.18 0.86	
▼ ₇₀ Г ₇	$T_{V,i} = 150 ^{\circ}\text{C}$	s calculations only		0.90	
V _{G7}	$V_D = 6 \text{ V}$	T _{v1} = 25°C	7	2.5	
	v _D = 0 v	$T_{VJ} = -40$ °C		2.6	
I _{G7}	V _D = 6 V			145	m/
	<i>D</i> -	$T_{VJ} = -40$ °C		200	
V _{GD}	T _{v,i} = 150 °C			0.2	
I _{GD}		D.C.		10	m/
I _L	t _p =30 μs	$T_{yy} = 25^{\circ}C$ $I_{g} = 0.45 \text{ A}$ $di_{g}/dt = 0.45 \text{ A/}\mu\text{s}$		300	m/
I _H	R _{GK} = ∞	$T_{VJ} = 25^{\circ}C$ $V_{D} = 6 \text{ V}$		200	m/
t _{gd}	$V_D = \frac{1}{2} V_{DRM}$	$T_{v_{J}} = 25^{\circ}C$		2	μ
	$I_{\rm G} = 0.5 {\rm A}$	$di_{G}/dt = 0.5 A/\mu$			
t _q	V _R = 100 V	$I_{T} = 200 \text{ A}$ -di/dt = 20 A/ μ s		150	μ
	$t_p = 200 \mu s$	$dv/dt = 20 V/\mu s V_D = \frac{2}{3} V drm T_{V,J} = 125 °C$			
(di/dt) _{ci}	repetitive	$I_{\tau} = 500$ A		150	A/µs
	non repetitive	·		500	A/µs
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.45 ^{\circ}\text{A/}\mu\text{s}$			
	$I_{G} = 0.45 \text{ A}$				
(dv/dt) _{cr}	$T_{VJ} = 150 ^{\circ}C$	$V_{DR} = \frac{2}{3} V_{DRM}$		1000	V/µs
	R _{GK} = ∞	method 1 (linear voltage rise)			
P _{GM}	$T_{VJ} = 150 ^{\circ}\text{C}$	$t_p = 30 \mu\text{s}$		120	W
		$t_p = 5E \mu s$		60	
P _{GAV}				8	
V _{RGM}				10	
T _{VJ}		-40		150	°C
I _{T(AV)}	$T_C = 100 ^{\circ}C$	180° rect.		204	P
	$T_{VJ} = {}^{\circ}C$	180° sine		tbd	Α
I _{TSM} *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		4750	A
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		5080	Α
	$T_{VJ} = 150 ^{\circ}\text{C}$	t = 10 ms (50) Hz, sine		4230	P
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		4530	P
Pt *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		112813	Α :
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		107097	A s
	T _{vJ} = 150 °C	t = 10 ms (50) Hz, sine		89465	A s
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		85162	A s
R _{thJC} *	DC current		0.2		K/V

^{*} Data according to assembled product MCC 132



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- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.